

CLAIMS

1 1. Device 1 for mounting at least two electrical components (4A, 4B) on a
2 printed circuit card (2), the card (2) comprising connection pads on both of its sides,
3 characterized in that the card (2) is traversed by holes (11-14) for receiving mounting
4 means that extend through the printed circuit card in order to mount the electrical
5 components (4A, 4B) on opposite sides of the card.

1 2. Device according to claim 1, characterized in that the mounting means
2 exert equal pressure on each side of the printed circuit card (2).

1 3. Device according to claim 1 or 2, characterized in that the mounting
2 means are standoffs (16-19), each standoff comprising on both of its ends a threaded part
3 capable of receiving a screw for attaching the integrated circuits (4A, 4B).

1 4. Device according to any of claims 1 through 3, characterized in that it
2 includes a plate (8) on each side of the printed circuit card, said plate (8) including
3 notches traversed by the standoffs, the shape of the holes and the standoffs preventing
4 any rotational movement of the standoffs for mounting and removal.

1 5. Device according to claim 3, characterized in that, on each side of the
2 printed circuit card (2), springs (25A-28A) and (25B-28B) are inserted between the head
3 of each respective screw (20A-23A) and (20B-23B) and the respective plate (24A, 24B),
4 one of the ends of the spring pressing against the respective plate (24A, 24B).

1 6. Device according to any of claims 1 through 5, characterized in that, on
2 each side of the printed circuit card, each standoff (16-19) is equipped with a spring with
3 the same stiffness coefficient in order to exert a uniform pressure capable of establishing
4 electrical contact between each electrical component (4A, 4B) and the printed circuit card
5 (2)

1 7. Device according to any of the preceding claims, characterized in that, on
2 each side of the printed circuit card 2, a heat sink (5A and 5B) is mounted on the

3 respective plate (24A, 24B), and in that a twist clip (27A, 27B) connects the respective
4 heat sink (5A, 5B) and plate (24A, 24B) so as to exert on this assembly a pressure force
5 independent of the pressure force produced by the springs.

1 8. Device according to any of the preceding claims, characterized in that the
2 electrical component is an integrated circuit whose electrical contact with the printed
3 circuit card is produced by pressure.

1 9. Tool (35) for mounting or removing an electrical component mounted on a
2 printed circuit card as defined in any of claims 1 through 8, characterized in that it
3 comprises means for exerting pressure on a first electrical component (4A) mounted on a
4 first side of the printed circuit card, in order to mount or remove a second electrical
5 component (4B) on the opposite side of the printed circuit card (2).

1 10. Tool (35) according to claim 9, characterized in that the means for
2 exerting pressure are springs (31, 32) whose axis coincides with the axis of the standoffs
3 (16-19).